

C2225X183JBRACTU

Specifications

Insulation Resistance

Aliases (C2225X183JBRAC7800)

SMD Comm X7R HV Flex, Ceramic, 0.018 uF, 5%, 630 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 2225, 3.2 mm



General Information	
Series	SMD Comm X7R HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Temperature Stable
Features	FT-CAP, Temperature Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	350 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	2225
L	5.9mm +/-0.75mm
W	6.4mm +/-0.4mm
Т	1.4mm +/-0.15mm
S	3.2mm MIN
В	0.7mm +/-0.35mm

	Capacitance	0.018 uF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	5%
	Voltage DC	630 VDC
	Dielectric Withstanding Voltage	945 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	X7R
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
	Dissipation Factor	2.5%1kHz1.0Vrms
	Aging Rate	3% Loss/Decade Hour: Referee

Time is 1000 Hours

55.5556 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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